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1

Electrical ratings

Symbol	Parameter	Value	Unit
V _{CBO}	Collector-base voltage (I _E = 0)	100	V
V _{CEO}	Collector-emitter voltage (I _B = 0)	80	V
V _{EBO}	Emitter-base voltage (I _C = 0)	5	V
۱ _C	Collector current	1	Α
I _{CM}	Collector peak current (t _P < 5ms)	1.5	Α
Ι _Β	Base current	0.1	Α
I _{BM}	Base peak current (t _P < 5ms)	0.2	A
P _{tot}	Total dissipation at T _{amb} = 25°C	1.6	W
T _{stg}	Storage temperature	-65 to 150	°C
ТJ	Max. operating junction temperature	150	°C

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R _{thj-amb}	Thermal resistance junction-ambient ⁽¹⁾ max	78	°C/W

1. Device mounted on PCB area of 1 cm².



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2 Electrical characteristics

($T_{case} = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Test Conditio	ons Min.	Тур.	Max.	Unit
I _{CBO}	Collector cut-off current	V _{CB} = 30V			100	nA
020	(I _E =0)	$V_{CB} = 30V;$ $T_j = 1$	25°C		10	μA
V _{(BR)CEO} ⁽²⁾	Collector-emitter breakdown voltage (I _B =0)	I _C = 20mA	80			V
V _{(BR)CBO}	Collector-base breakdown voltage (I _E =0)	I _C = 100μΑ	100			V
V _{(BR)EBO}	Emitter-base breakdown voltage (I _C =0)	I _E = 10μΑ	5			v
V _{CE(sat)} ⁽²⁾	Collector-emitter saturation voltage	I _C = 500mA I _B =	50mA		0.5	V
V _{BE(on)} ⁽²⁾	Base-emitter on voltage	I _C = 500mA V _{CE}	= 2V		1	V
	DC current gain	$I_C = 5mA$ V_{CE}	= 2V 40			
h _{FE} ⁽²⁾		$I_C = 150 \text{mA}$ V_{CE}	= 2V 100		250	
		$I_C = 500 \text{mA}$ V_{CE}	= 2V 25			

Table 3. Electrical characteristics

Note (2) Pulsed duration = 300 μ s, duty cycle \leq 1.5%

DG15940

T_J =125 °C

0.6

I_c(A)

2.1 Electrical characteristics (curves)

Figure 1. DC current gain

Figure 2. Collector-emitter saturation voltage

T_J =25 °C

 $h_{FE} = 10$

 $T_J = -40$ °C

0.4

0.2

V_{CE(sat)} (V)

0.1

0.01 L 0.1

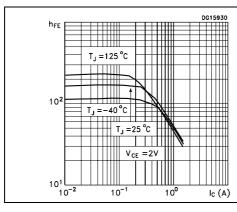
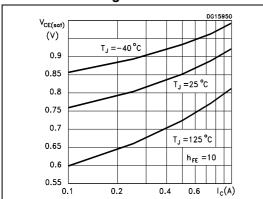


Figure 3. Base-emitter saturation voltage



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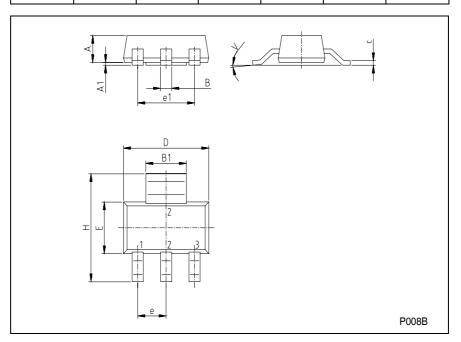
3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com



SUT-223 MECHANICAL DATA							
DIM.		mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А			1.80			0.071	
В	0.60	0.70	0.80	0.024	0.027	0.031	
B1	2.90	3.00	3.10	0.114	0.118	0.122	
с	0.24	0.26	0.32	0.009	0.010	0.013	
D	6.30	6.50	6.70	0.248	0.256	0.264	
е		2.30			0.090		
e1		4.60			0.181		
Е	3.30	3.50	3.70	0.130	0.138	0.146	
Н	6.70	7.00	7.30	0.264	0.276	0.287	
۷			10 [°]			10 [°]	
A1		0.02					

SOT-223 MECHANICAL DATA



4 Revision history

Table 4. Revision history

Date	Revision	Changes	
02-Sep-2004	1	Initial release.	
26-May-2006	2	New template	
14-Jun-2006	3	3 Three curves has been added on page 5.	



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